# **CHIPQUIK®**

## NCSWLF.015 0.2OZ

Datasheet revision 1.3 www.chipquik.com

### Solder Wire SAC305 No-Clean with 2.2% Flux Core 0.2oz Tube

#### **Product Highlights**

No-Clean Synthetic Flux Core

The clear, non-corrosive, non-conductive residue is meant to be left on the board.

2.2% flux core

Halogen content: None

**RoHS 3 and REACH compliant** 



Alloy: Sn96.5/Ag3.0/Cu0.5
Wire Diameter: 0.015" (0.38mm)
Flux Type: No-Clean Synthetic

Flux Classification: ROL0

Melting Point: 217-220°C (423-428°F)

Packaging: 0.2 oz Tube Shelf Life: >60 months



#### **Test Results**

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

#### **Conforms to the following Industry Standards:**

J-STD-004B, Amendment 1 (Solder Fluxes):

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):

RoHS 3 Directive (EU) 2015/863:

Yes